

Material Content Data Sheet

RoHS

Sales Product Name	IPD400N06N G	**Issued**	24. February 2022
MA#	MA005701023		
Package	PG-TO252-3-311	**Weight***	313.60 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.550	0.49	0.49	4944	4944
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		457	
	non noble metal	copper	7440-50-8	143.098	45.63	45.69	456311	456905
wire	non noble metal	aluminium	7429-90-5	1.288	0.41	0.41	4107	4107
encapsulation	inorganic material	antimonytrioxide	1309-64-4	2.000	0.64		6376	
	plastics	brominated resin	-	2.142	0.68		6832	
	organic material	carbon black	1333-86-4	2.285	0.73		7287	
	plastics	epoxy resin	-	19.282	6.15		61487	
	inorganic material	silicondioxide	60676-86-0	117.121	37.35	45.55	373475	455457
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11926	11926
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277
solder	non noble metal	tin	7440-31-5	0.032	0.01		103	
	noble metal	silver	7440-22-4	0.040	0.01		129	
	non noble metal	lead	7439-92-1	1.543	0.49	0.51	4920	5152
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.12	6.13	61153	61232
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com